



Cypress Semiconductor Corporation, 198 Champion Court, San Jose, CA 95134. Tel: (408) 943-2600

## PRODUCT INFORMATION NOTIFICATION

**PIN:** PIN200302

**Date:** January 15, 2020

**Subject:** Ejector Pin Mark Change for Select 32-LQFP Package Assembled at TFME

**To:** FUTURE ELECTRONICS  
FUTURE ELE  
pcn.system2@future.ca

**Change Type:** Minor

### **Description of Change:**

Cypress announces the change of ejector pin mark for select 32-LQFP package assembled at TongFu Microelectronics Co., Ltd (TFME, No.288, Chongchuan Road, Nantong, Jiangsu, China). The change is from existing one ejector-pin mark to two ejector pin marks at package bottom and additional two ejector-pin marks at package top. Marking needs to be shifted to cater for additional ejector-pin marks. The ejector-pin mark size is also reduced from 2.5mm to 1.0mm diameter. Pin1 mark position unchanged but reduced from 1.2mm to 0.8mm diameter.

The ejector-pin mark change is due to change of standard lead frame to high density lead frame but will not affect TFME's stringent quality and reliability requirements.

There are no changes to ordering part numbers. Product datasheets remain the same and can be downloaded from the Cypress Website ([www.cypress.com](http://www.cypress.com)).

### **Benefit of Change:**

This qualification is part of Cypress' continuous improvement in our flexible manufacturing initiative providing Cypress with the added capability to meet upside market demand, reduce business continuity risk, and ensure consistent and reliable delivery to customers in dynamic, changing market conditions.

### **Part Numbers Affected: 18**

See the attached 'Affected Parts List' file for a list of all part numbers affected by this change. Note that any new parts that are introduced after the publication of this PIN will include all changes outlined in this PIN.

**Qualification Status:**

This change has been qualified through a series of tests documented in the Qualification Test Plan QTP#173401 This qualification report can be found as an attachment to this PCN or by visiting [www.cypress.com](http://www.cypress.com) and typing the QTP number in the keyword search window.

**Approximate Implementation Date:**

This change will be implemented with the date of this notification.

**Anticipated Impact:**

Products manufactured are completely compatible with existing product from form, fit, functional, parametric, and quality performance perspectives.

Cypress also recommends that customers take this opportunity to review these changes against current application notes, system design considerations and customer environment conditions to assess impact (if any) to their application.

**Method of Identification:**

Cypress maintains traceability of product to wafer level, including wafer fabrication location, through the lot number marked on the package.

**Response Required:**

This is an information only announcement. No response is required.

For additional information regarding this change, contact your local sales representative or contact the PCN Administrator at [pcn\\_adm@cypress.com](mailto:pcn_adm@cypress.com).

Sincerely,

Cypress PCN Administration



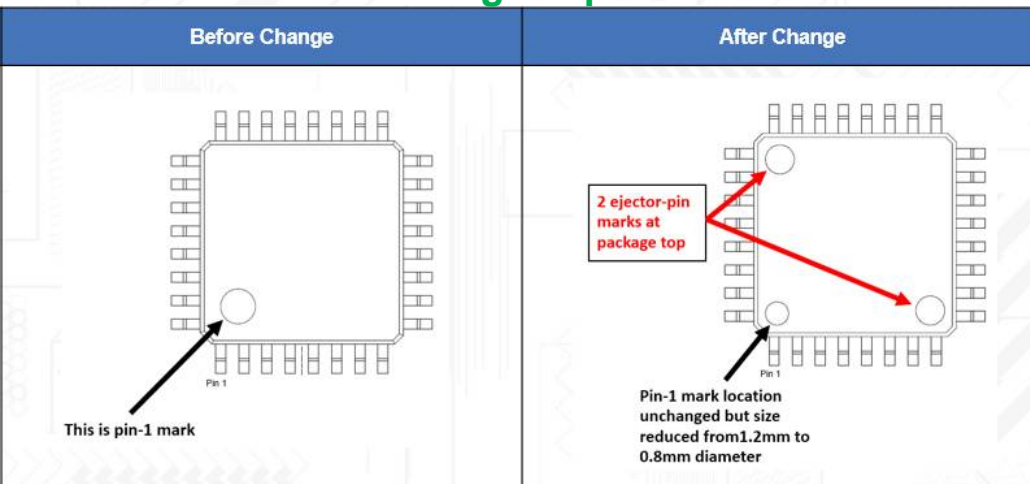
# Select 32-LQFP Package Ejector Pin Mark Change



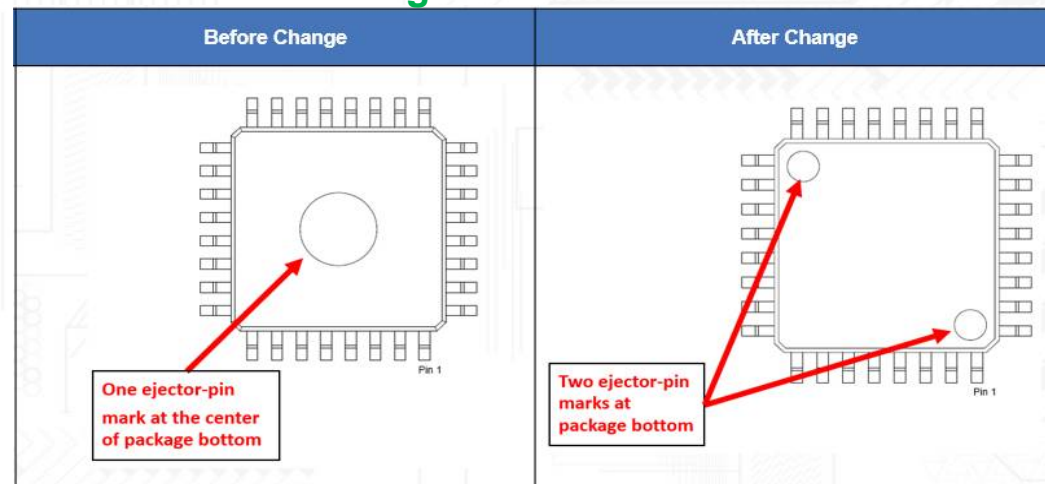
## Changing Points - Pin 1 size, number of ejector pins & ejector pin location

- a) Pin 1 size reduced from 1.2mm diameter to 0.8mm.
- b) At package top surface, added 2 ejector pin marks.
- c) At package bottom surface, changed from 1 ejector pin mark (2.5mm) at the center to 2 smaller ejector pin marks (1.0mm) at the corners

### Package Top View

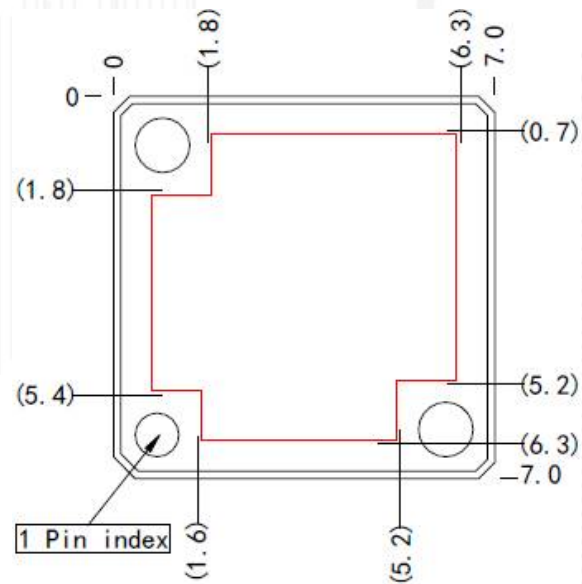
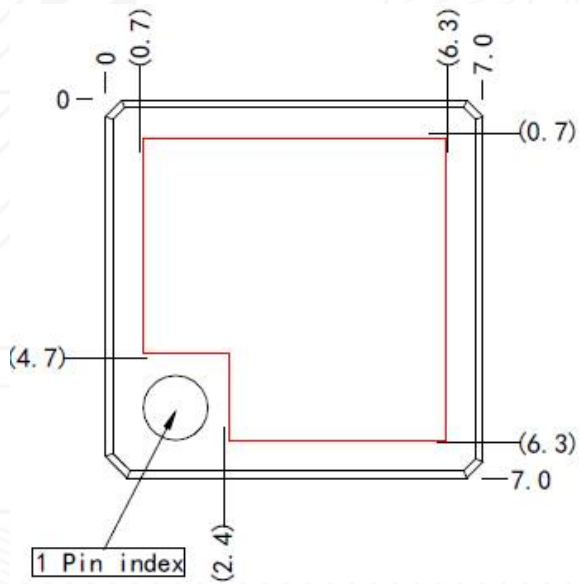


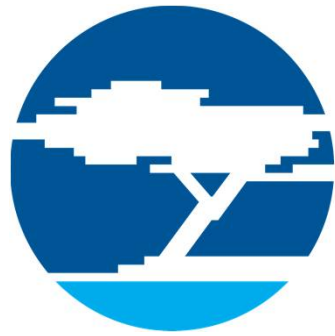
### Package Bottom View



## Marking Position Shift

Picture below shows on revised marking area for LQFP32 to avoid the e-pin mark at package top.





**CYPRESS<sup>®</sup>**

**EMBEDDED IN TOMORROW<sup>™</sup>**